

having a lower surface covered by the second metal coating and side surfaces uncovered by the second metal coating, said chip package further comprising a third metal coating covering the side surfaces of the second portion and the second metal coating.

18. The chip package of claim 15, said piece has a first portion embedded in the package body and a second portion located outside the package body, both the first and second portions of said piece have concave profiles.

B1 19. The chip package of claim 11, wherein each of the connection pads is a piece made of a single material which projects integrally from within the package body outwardly and beyond a bottom surface of the package body.

20. The chip package of claim 19, wherein said single material is copper.

21. The chip package of claim 19, wherein said piece has a first portion embedded in the package body and a second portion located outside the package body, said second portion having a lower surface covered by the second metal coating and side surfaces uncovered by the second metal coating, said chip package further comprising a third metal coating covering the side surfaces of the second portion and the second metal coating.

22. The chip package of claim 19, said piece has a first portion embedded in the package body and a second portion located outside the package body, both the first and second portions of said piece have concave profiles. --

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